(12) United States Design Patent

Lin et al.

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(54) **THERMAL MODULE**

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(73) Assignee: **ASUSTek Computer Inc.**, Taipei (TW)

(**) Term: **14 Years**

(21) Appl. No.: **29/196,439**

(22) Filed: **Dec. 31, 2003**

(30) **Foreign Application Priority Data**

Oct. 15, 2003 (TW) 92306268

(51) **LOC (8) Cl.** **13-03**

(52) **U.S. Cl.** **D13/179**

(58) **Field of Search** D13/179; 165/80.3, 165/121, 122, 146, 104.33, 180, 185; 174/16.3; 257/706, 707, 718–722; 361/271, 274.3, 695, 697, 700, 702, 704, 709, 710, 711, 514, 719

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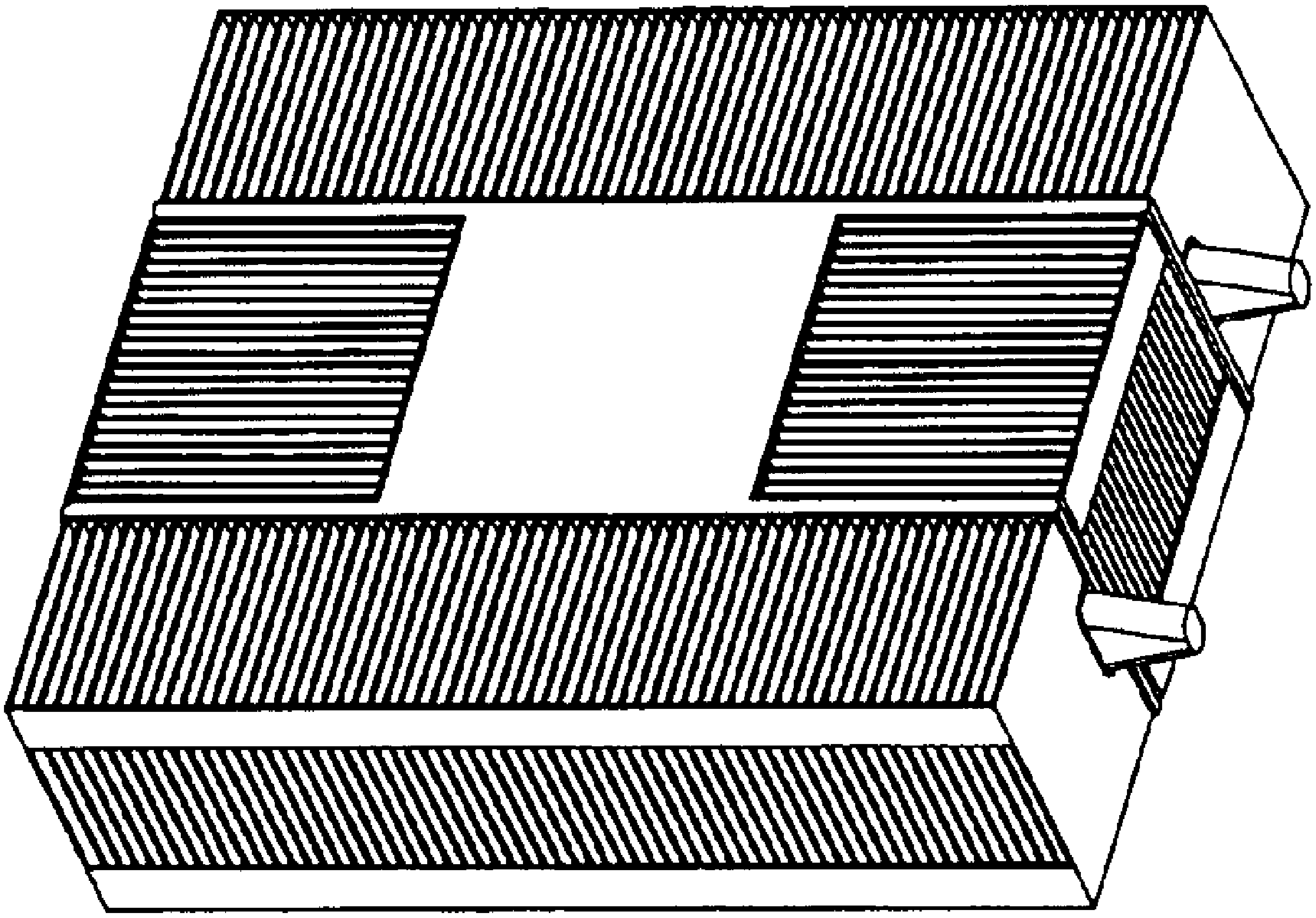
(57) **CLAIM**

The ornamental design for a thermal module, as shown and described.

DESCRIPTION

FIG. **1** is a perspective view of a thermal module showing our new design;
FIG. **2** is a front elevational view thereof;
FIG. **3** is a left side elevational view thereof;
FIG. **4** is a right side elevational view thereof;
FIG. **5** is a top plan view thereof;
FIG. **6** is a bottom plan view thereof; and,
FIG. **7** is a rear elevational view thereof.

1 Claim, 7 Drawing Sheets



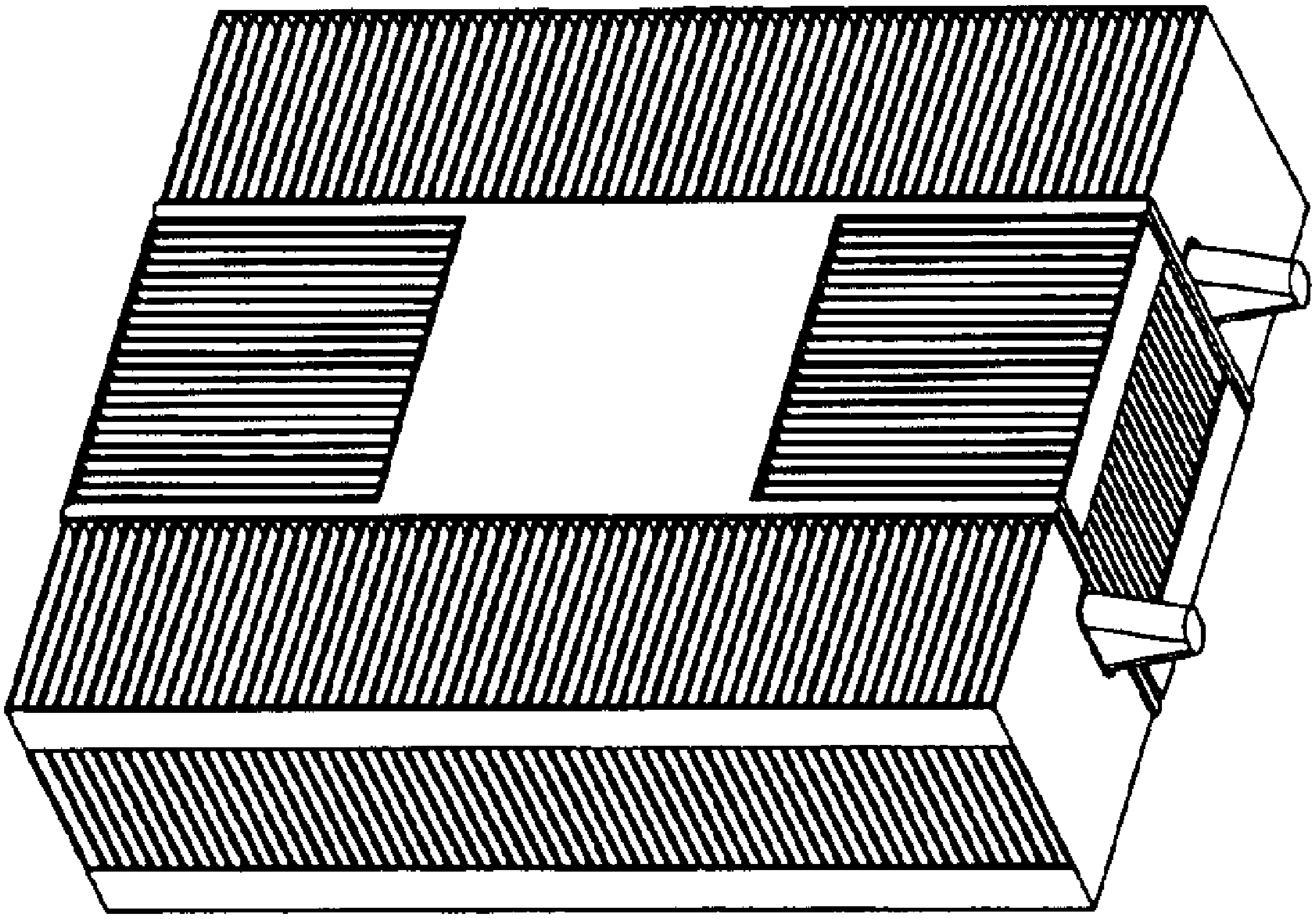


FIG. 1

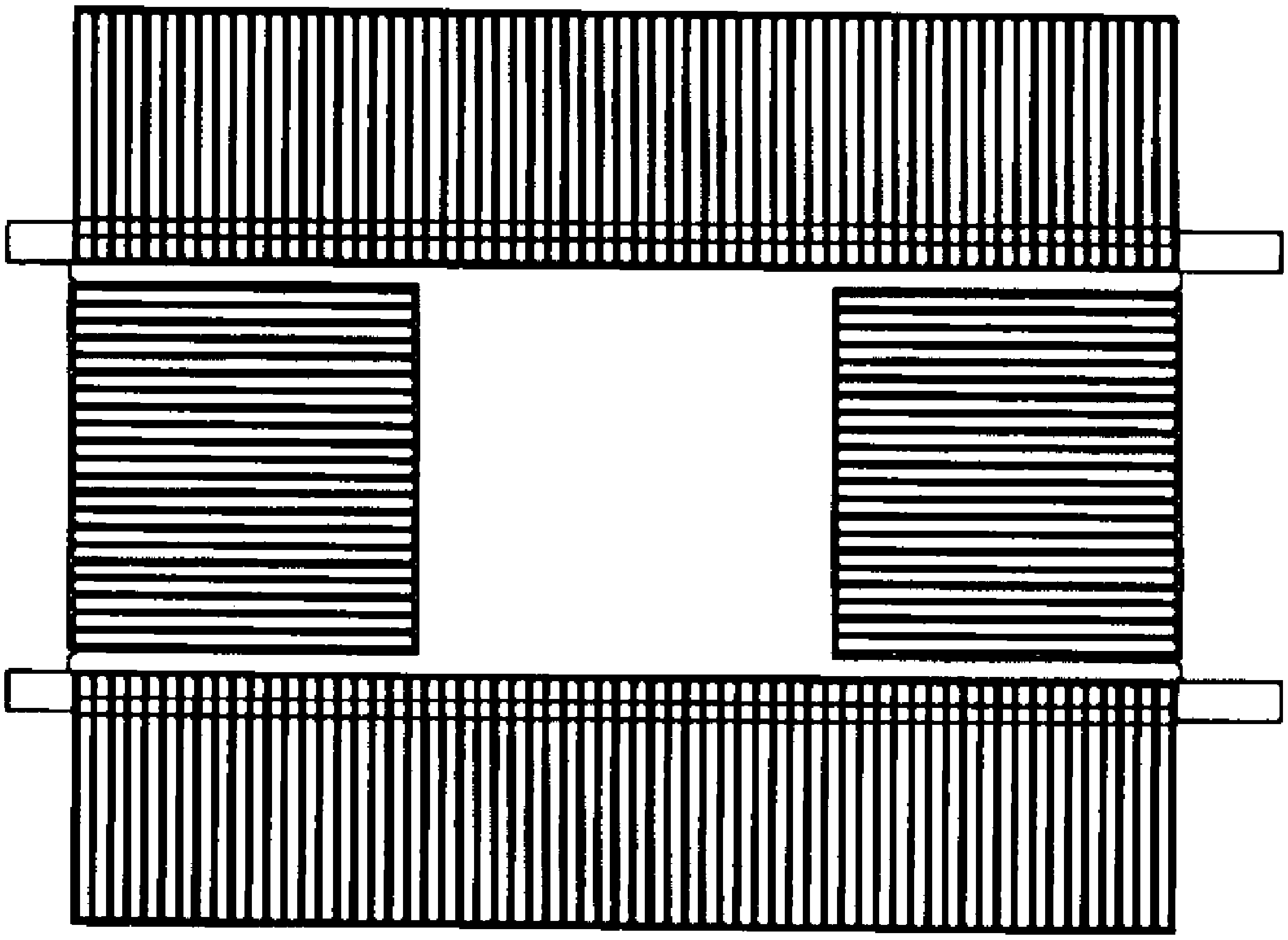


FIG. 2

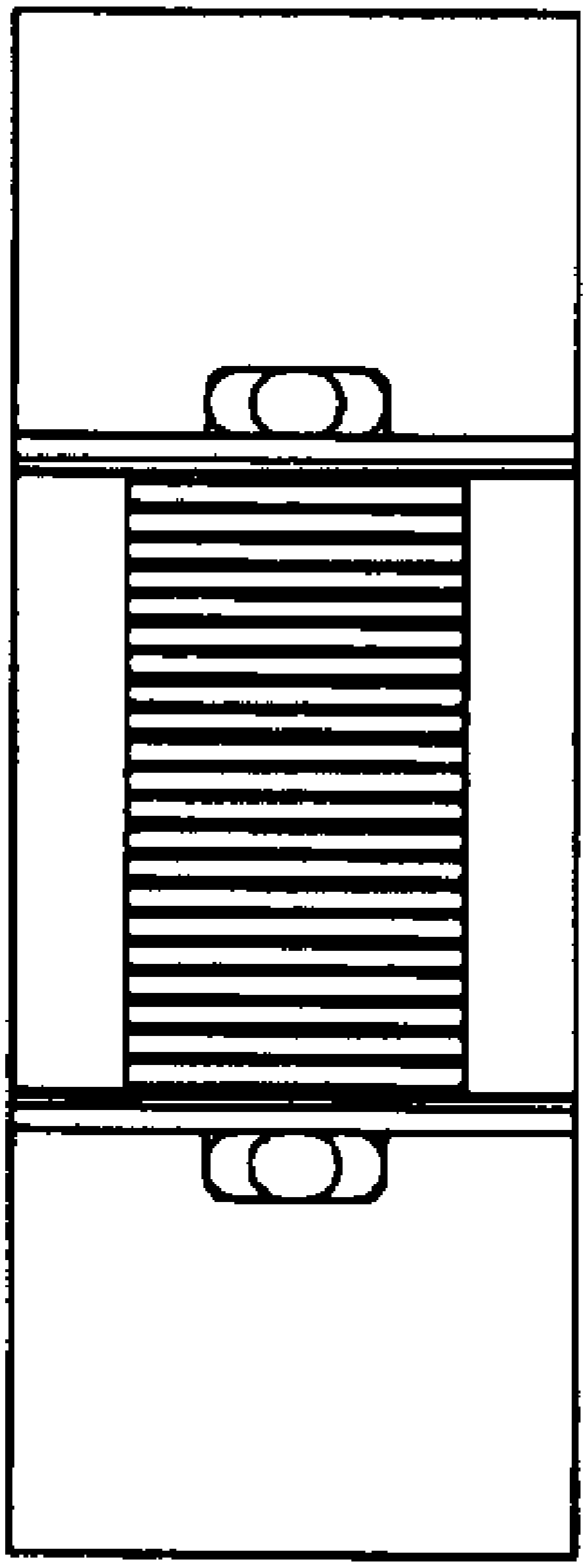


FIG. 3

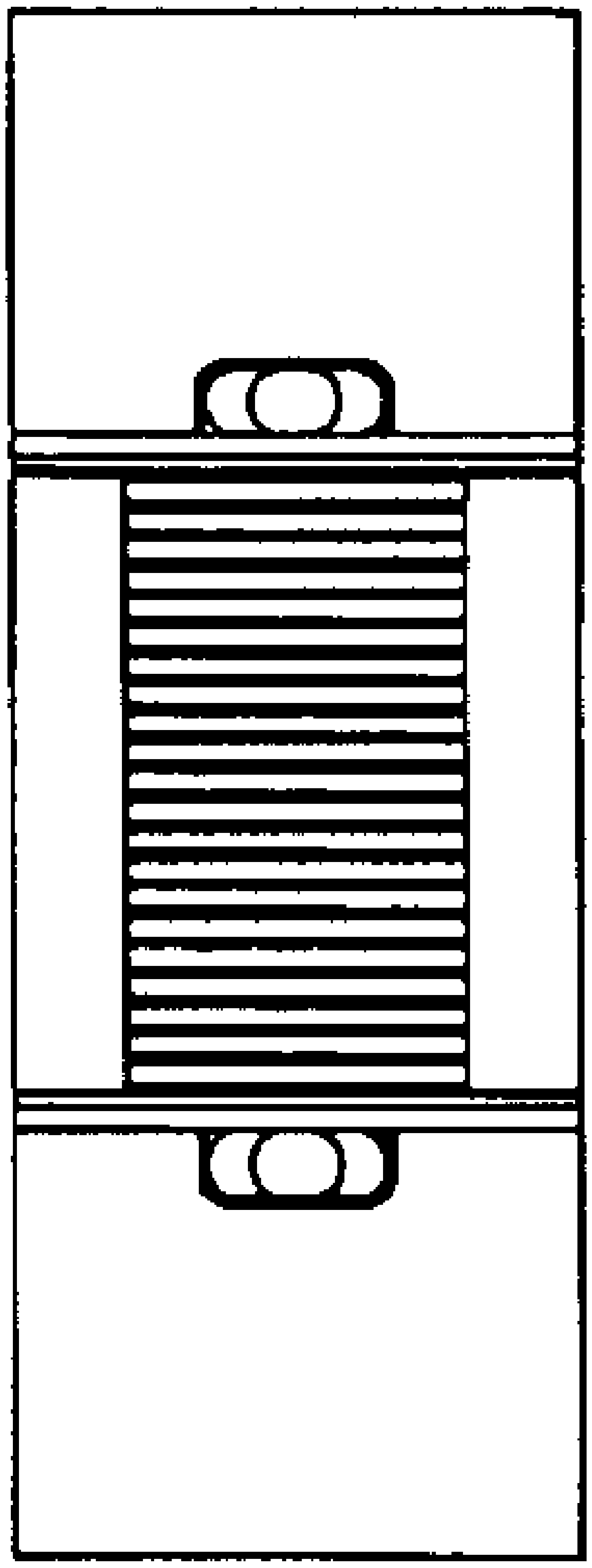


FIG. 4

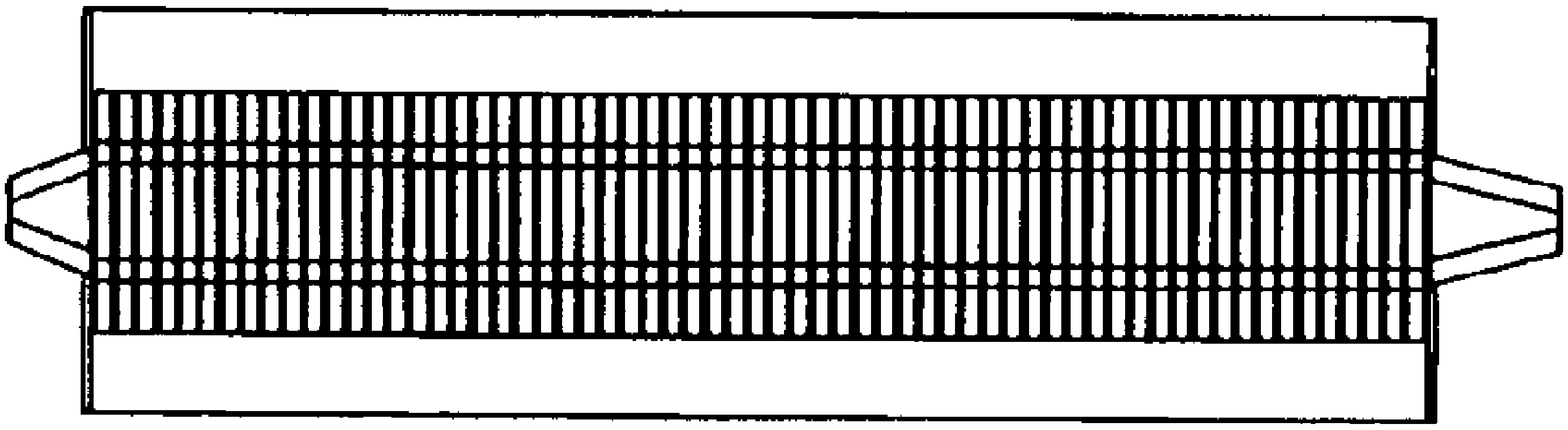


FIG. 5

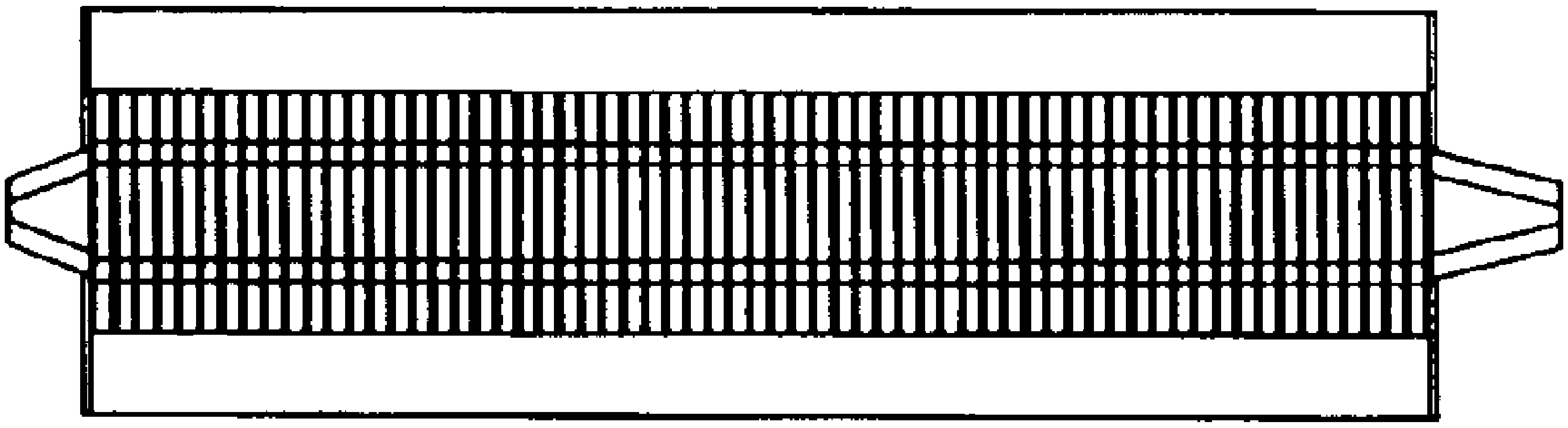


FIG. 6

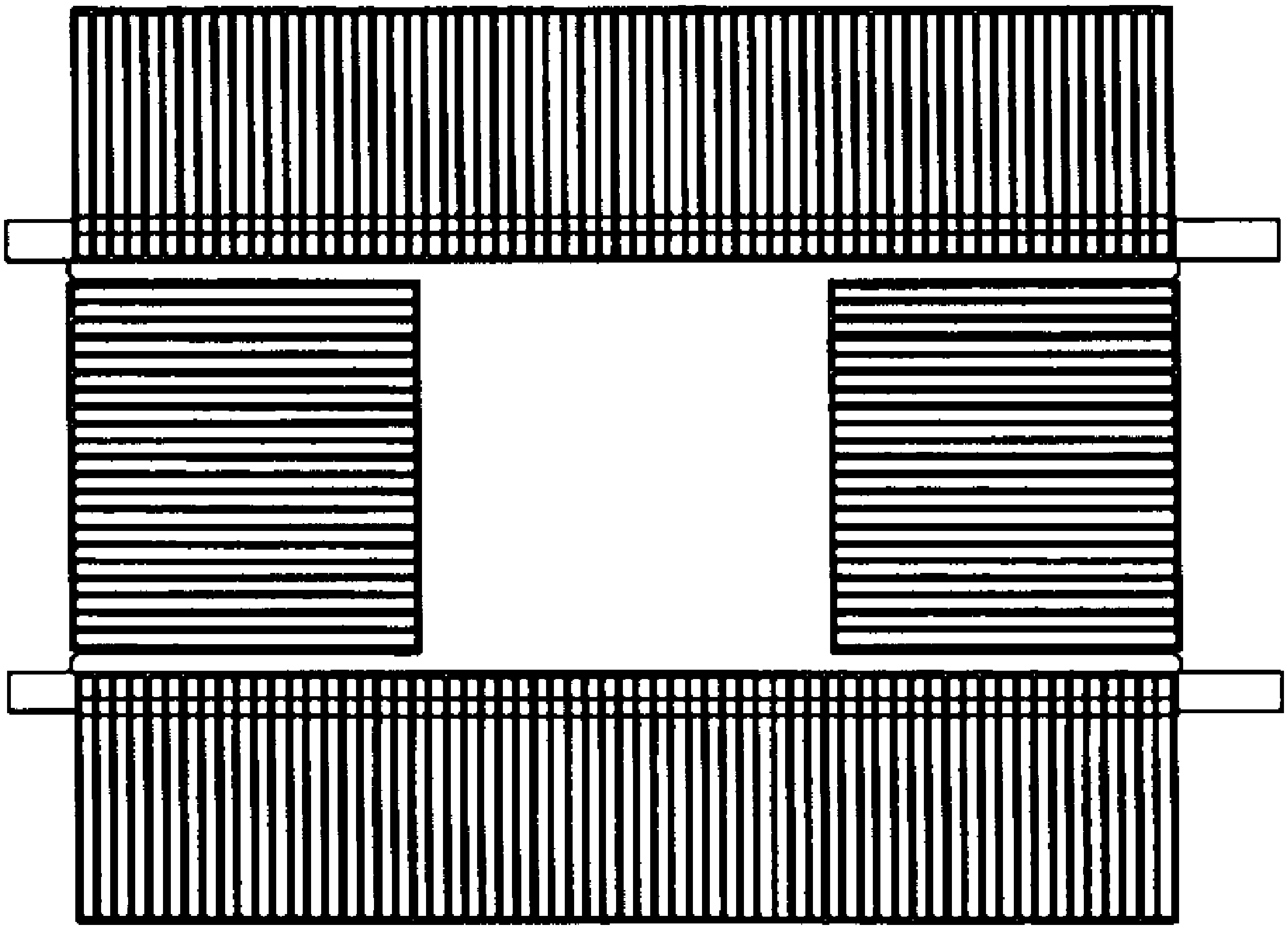


FIG. 7